

REMARKS

Claims 1, 2, and 11 have been amended. Claims 1-23 and 35-38 are pending in this application.

Claims 1, 5-19 are rejected under 35 U.S.C. § 102(e) as being anticipated, or in the alternative, under 35 U.S.C. § 103(a) as being obvious over Lam, U.S. Patent No. 6,344,401 B1 (“Lam”). Applicants respectfully traverse this rejection and request reconsideration.

Amended independent claims 1 and 11 recite “method[s] of making semiconductor device packages.” The methods of amended independent claims 1 and 11 each includes the step of “providing conductive structures in contact with a top surface of said dielectric layer.” Lam fails to disclose or suggest such a step. Instead, Lam teaches attaching semiconductor dice to a semiconductor wafer using an adhesive material, such as epoxy or thermo-plastic. According to Lam, the adhesive is placed on the portion of the wafer where the dice are to be placed. (Col. 4, lines 1-15; FIGS. 6-8). Thus, Lam teaches placing semiconductor dice in contact with a surface of the adhesive, not “providing conductive structures in contact with a top surface of said dielectric layer,” as recited in amended independent claims 1 and 11. Claims 5-10 and 12-18 depend from independent claims 1 and 11, respectively, and are believed to be allowable for at least the same reasons as claims 1 and 11.

Independent claim 19 recites a “method of making semiconductor device packages.” The method includes the step of “simultaneously dicing said wafer and said dielectric tape.” Lam does not teach or suggest dicing a wafer and a dielectric tape at the same time. The Office Action fails to point to where Lam teaches or suggests a dielectric tape. Lam only teaches that a paste or pre-form adhesive material is placed on larger dice 24, 25 of a wafer where smaller, singulated dice 14, 15 are to be attached. (Col. 4, lines 1-15; FIGS. 6-8). Also, Lam shows that lateral edges along which the larger dice 24, 25 are cut include the wafer and an encapsulant 80, not an adhesive material, much less a

dielectric tape. (FIGS. 8-10). Therefore, even if Lam's adhesive layer were equivalent to the dielectric tape of independent claim 19, Lam would fail to teach or suggest "simultaneously dicing said wafer and said dielectric tape."

Claims 2 and 3 are rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Beyne et al. U.S. Patent No. 6,566,745 B1 ("Beyne"). Applicants respectfully traverse this rejection and request reconsideration. As noted above, Lam fails to teach or suggest all limitations of independent claim 1. Beyne is cited in the Office Action for other reasons. Claims 2 and 3 depend from independent claim 1 and are believed to be allowable for at least the same reasons.

Claim 4 is rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Beyne and in further view of Lam U.S. Patent No. 5,137,836 ("Lam '836"). Applicants respectfully traverse this rejection and request reconsideration. As noted above, Lam fails to teach or suggest all limitations of independent claim 1. Beyne and Lam '836 are cited in the Office Action for other reasons. Claim 4 depends from independent claim 1 and is believed to be allowable for at least the same reasons.

Claim 20 is rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Gaynes et al. U.S. Patent No. 6,165,885 ("Gaynes"). Applicants respectfully traverse this rejection and request reconsideration. As noted above, Lam fails to teach or suggest all limitations of independent claim 19. Gaynes is cited in the Office Action for other reasons. Claim 20 depends from independent claim 19 and is believed to be allowable for at least the same reasons.

Claims 21-23 are rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Gaynes and in further view of Huddleston et al. U.S. Patent No. 5,834,320 ("Huddleston"). Applicants respectfully traverse this rejection and request reconsideration. As noted above, Lam fails to teach or suggest all limitations of independent claim 19.

Gaynes and Huddleston are cited in the Office Action for other reasons. Claims 21-23 depend from independent claim 19 and are believed to be allowable for at least the same reasons.

Claims 35 and 37 are rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Kobayashi et al. U.S. Patent No. 4,781,969 (“Kobayashi”). Applicants respectfully traverse this rejection and request reconsideration.

Independent claim 35 recites a “method of handling a plurality of semiconductor devices arrayed in a semiconductor wafer.” The claimed method includes the step of “adhering said wafer to a flexible substrate.” Neither Lam nor Kobayashi teach or suggest such a step. As noted by the Office Action, Lam is silent about adhering a wafer to a flexible substrate. (Office Action at 7). The Office Action asserts that Kobayashi discloses a printed circuit board “with (35).....adhering said wafer to a flexible substrate.” (Office Action at 8). Kobayashi, however, discloses affixing a composite metal layer to a flexible substrate, not a wafer. (Col. 1, lines 38-43). Claim 37 depends from independent claim 35 and is believed to be allowable for at least the same reasons.

Claims 36 and 38 are rejected under 35 U.S.C. § 103(a) as being obvious over Lam in view of Kobayashi and in further view of Lam ‘836. Applicants respectfully traverse this rejection and request reconsideration. As noted above, Lam and Kobayashi, even when considered in combination, fail to teach or suggest all limitations of independent claim 35. Lam ‘836 is cited in the Office Action for other reasons. Claims 36 and 38 depend from independent claim 35 and are believed to be allowable for at least the same reasons.

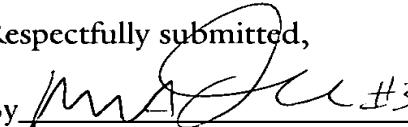
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In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

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Respectfully submitted,

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